IBM zEnterprise

zEnterprise.

A New Dimension in Computing

IBM Hardware news

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Information technology today: Limitations



- **§** Business processes and the applications that support them are becoming more service oriented, modular in their construction, and integrated.
- § The components of these services are implemented on a variety of architectures and hosted on heterogeneous IT infrastructures.
- § Approaches to managing these infrastructures along the lines of platform architecture boundaries cannot optimize: alignment of IT with business objectives; responsiveness to change; resource utilization; business resiliency; or overall cost of ownership.
- **§** Customers need better approach: The ability to manage the IT infrastructure and Business Application as an integrated whole.



Emerging Applications with Special-Purpose Capabilities

Future objectives include extended application integration and optimization



Both General and Special Purpose capabilities are needed



Cloud Computing





zEnterprise value pyramid





Today's Environment

Today... Many System z shops run their core, data-sensitive business processes on System z but also maintain distributed servers to accommodate a variety of processing that interacts with mainframe resources.



- § The <u>mainframe</u> has hosted most of the world's business data and executed a majority of core business transactions
- § The mainframe is best suited for applications that require the highest levels of:
 - Reliability
 - Security
 - Performance
 - Availability
 - Service
 - Scalability
- § However, the mainframe is not optimized for all workloads



- § There are particular industry application where <u>distributed</u> topology is the standard.
- **§** Distributed environments are suited for applications where:
 - High levels resource sharing is not required
 - The workload is
 - CPU intensive
 - Does not require high levels of data sharing
 - Highest levels of availability are not required
- **§** Other Distributed System Characteristics -
 - Multiple management interfaces
 - Redundancy required for availability
 - On-site assembly
 - End-user service for problem resolution



IBM zEnterprise System The integration of Superior technologies

zEnterprise Unified Resource Manager

- Unifies resources, extending System z qualities of service across the infrastructure
- Install, Monitor, Manage, Optimize, Diagnose & Service



zEnterprise BladeCenter Extension

IBM Blades

 Runs app unchanged and supports what you know.
 Logical device integration between System z and distributed resources

Optimizers

 Workload specific accelerators to deliver a lower cost per transaction, appliance for example IBM Smart Analytics Optimizer

zEnterprise 196

- The industry's fastest and most scalable enterprise server
- Ideally suited for large scale data and transaction serving and mission critical enterprise applications



Built on this construct – zEnterprise – Innovation at every level

	IBM	АРР	APP	APP	АРР	APP	АРР		
Service Management		MIDDLEWARE							
		MULTIPLE OPERATING SYSTEMS e.g., z/OS, z/TPF, z/VSE, z/VM,			ΑΙΧ	Linux on System x*			
Unified Resource Manager			Linux on z		VII	RTUALIZ	ZATION		
Platform Management	sprise	FIRMWARE							
Hardware Management	zEnte	S	ystem z		Power®	Syste	em x*	IBM Appliances	

Focused, collaborative innovation

A "complete systems" approach

* All statements regarding IBM future direction and intent are subject to change or withdrawal without notice, and represents goals and objectives only.



z196 and zBX Hardware Components



§ New System z Machine Types:

- CPC = 2817
- zBX = 2458 Model 002
- Customer supplied IBM System x* and POWER7 Blades

§ Key points:

- 1. CPC Availability and Integrity
- 2. Independent Lifecycles
 - Asynchronously Upgradeable
 - Enhancements not tied to CPC HW
- 3. Data availability not tied to single CPC
 - Shareable between CPCs
- 4. Growth
- 5. System z service

^{*}All statements regarding IBM's plans, directions, and intent are subject to change or withdrawal without notice. Any reliance on these Statements of General Direction is at the relying party's sole risk and will not create liability or obligation for IBM.



IBM Multi-Architecture Virtualization – "Fit for Purpose" System z Multi-System, Federated Hypervisor Configuration

- **§** System z futures: hosting a federation of platform management functions, including:
 - Resource monitoring
 - Workload management
 Availability management

- Image management
- Energy management
- § Integrates with hardware management and virtualization functions
- § Controls hypervisors and management agents on blades
- § Open integration to enterprise-level management software





zEnterprise System – 196 + zBX + Unified Resource Manager



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z196 zBX Model 002 – Communications





Z11 (buildt in 1956, Konrad Zuse), so lets have a look at z196





z196 performance and scalability

Think Inside the box! Think System z Qualities of Service!

§ zEnterprise ensembles – Multiple nodes

- Node - z196 with or without zBX

§ zEnterprise Unified Resource Manager

§ Multiple architectures

- z/Architecture®
- Power Architecture® POWER7
- X-Architecture®

§ z196

- -Largest z196 model
 - 1.6x compared to z10 EC E64
- -Equivalent n-ways
 - 1.4x compared to z10 EC
- -With compiler optimization additional 30% additional for some CPU intensive work







z196 Overview



[^] Machine Type

- 2817

5 Models

- M15, M32, M49, M66 and M80

Processor Units (PUs)

- 20 (24 for M80) PU cores per book
- Up to 14 SAPs per system, standard
- 2 spares designated per system
- Dependant on the H/W model up to 15,32,49,66 or 80 PU cores available for characterization
 - Central Processors (CPs), Integrated Facility for Linux (IFLs), Internal Coupling Facility (ICFs), System z Application Assist Processors (zAAPs), System z Integrated Information Processor (zIIP), optional - additional System Assist Processors (SAPs)
- Sub-capacity available for up to 15 CPs
 - 3 sub-capacity points

Memory

- System Minimum of 32 GB
- Up to 768 GB per book
- Up to 3 TB for System and up to 1 TB per LPAR
 - Fixed HSA, standard
 - 32/64/96/112/128/256 GB increments

I/O

- Up to 48 I/O Interconnects per System @ 6 GBps each
- Up to 4 Logical Channel Subsystems (LCSSs)
- **STP optional** (No ETR)



z196 Out of Order (OOO) Value

§ OOO yields significant performance benefit for compute intensive apps through

- -Re-ordering instruction execution
 - Later (younger) instructions can execute ahead of an older stalled instruction
- -Re-ordering storage accesses and parallel storage accesses

§ OOO maintains good performance growth for traditional apps





z196 Multi-Chip Module (MCM) Packaging

§ 96mm x 96mm MCM

- 103 Glass Ceramic layers
- 8 chip sites
- 7356 LGA connections
- 20 and 24 way MCMs
- Maximum power used by MCM is 1800W



§CMOS 12s chip Technology

- PU, SC, S chips, 45 nm
- 6 PU chips/MCM Each up to 4 cores
 - One memory control (MC) per PU chip
 - 23.498 mm x 21.797 mm
 - 1.4 billion transistors/PU chip
 - L1 cache/PU core
 - 64 KB I-cache
 - 128 KB D-cache
 - L2 cache/PU core
 - 1.5 MB
 - L3 cache shared by 4 PUs per chip 24 MB
 - 5.2 GHz
- 2 Storage Control (SC) chip
 - 24.427 mm x 19.604 mm
 - 1.5 billion transistors/SC chip
 - L4 Cache 96 MB per SC chip (192 MB/Book)
 - L4 access to/from other MCMs
- 4 SEEPROM (S) chips
 - 2 x active and 2 x redundant
 - Product data for MCM, chips and other engineering information
- Clock Functions distributed across PU and SC chips
 - Master Time-of-Day (TOD) function is on the SC



z196 Quad Core PU Chip Detail



- § 12S0 45nm SOI Technology
 - 13 layers of metal
 - 3.5 km wire
- § 1.4 Billion Transistors

- § Chip Area 512.3mm²
 - 23.5mm x 21.8mm
 - 8093 Power C4's
 - 1134 signal C4's

§ Up to Four active cores per chip

- 5.2 GHz
- L1 cache/ core
 - 64 KB I-cache
 - 128 KB D-cache
- 1.5 MB private L2 cache/ core
- § Two Co-processors (COP)
 - Crypto & compression accelerators
 - Includes 16KB cache
 - Shared by two cores

§ 24MB eDRAM L3 Cache

- Shared by all four cores
- § Interface to SC chip / L4 cache
 - 41.6 GB/sec to each of 2 SCs
- § I/O Bus Controller (GX)
 - Interface to Host Channel Adapter (HCA)
- § Memory Controller (MC)
 - Interface to controller on memory DIMMs
 - Supports RAIM design



z196 SC Chip Detail

§ 12S0 45nm SOI Technology

- 13 layers of metal

§ Chip Area – 478.8mm^2

- 24.4mm x 19.6mm
- 7100 Power C4's
- 1819 signal C4's

§ 1.5 Billion Transistors

 1 Billion cells for eDRAM

§ eDRAM Shared L4 Cache

- 96 MB per SC chip
- 192 MB per Book

§ 6 CP chip interfaces

- § 3 Fabric interfaces
- § 2 clock domains
- § 5 unique chip voltage supplies





Conclusion or what is IBM zEnterprise system all about?

Re-write the rulebook and set new standards for business-centric IT with IBM System z, to be the world's premier workload-optimized platform for enterprise applications.



Our Vision:

Deliver the best of all worlds - Mainframe, UNIX[®], x86 and single function processors - integrated in a single system for ultimate flexibility and simplicity to optimize service, risk, and cost across multiple heterogeneous workloads.



Thank you for your audience !

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